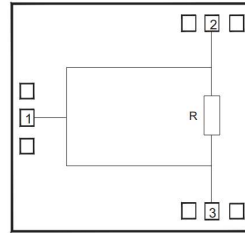


Performance

- Frequency: 2-18GHz
- Insertion loss: 1.0dB
- Chip size: 2.00*2.05*0.1mm

Function Diagram

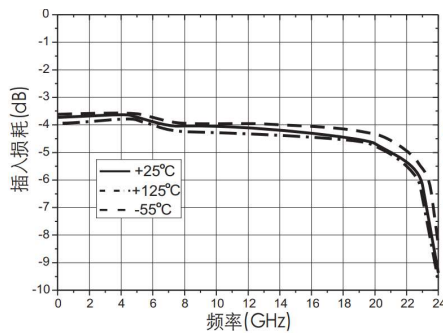


Electrical Specifications (Ta=+25°C, 50Ω system)

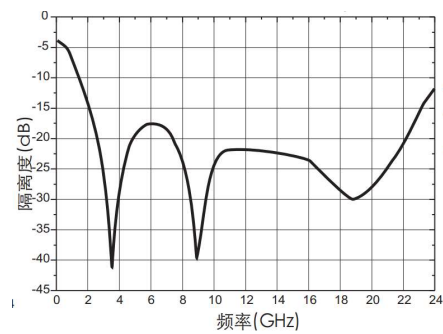
Parameter		Min	Typical	Max	Unit
Frequency Range		2-18			GHz
Insertion Loss	2-10GHz	-	0.8	1.2	dB
	10-18GHz	-	1.2	1.4	
IL Ripple		-	±0.4	-	dB
Isolation		15	20	-	dB
VSWRout		12	20	-	dB
Isolation		14	20	-	dB

Test Curves

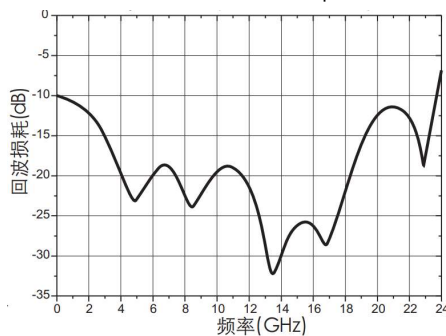
Insertion loss vs. Freq



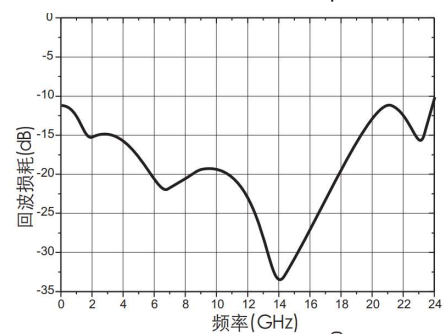
Isolation vs. Freq



VSWRin vs. Freq



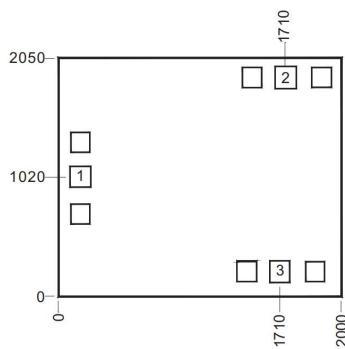
VSWRout vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1A

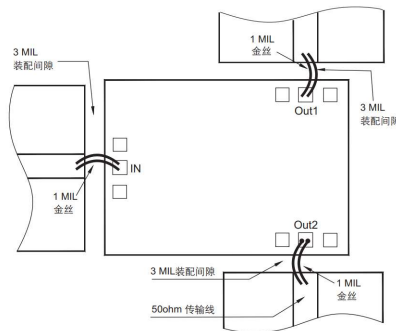
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 100*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

Number	Description
IN	RF input port, connect to 50ohm system
Out1 Out2	RF output port, connect to 50ohm system
GND	Bottom must be grounded